RoHS



Vishay General Semiconductor

Standard Avalanche SMD Rectifier



DO-214AC (SMA)

PRIMARY CHARACTERISTICS						
I _{F(AV)}	1.5 A					
V_{RRM}	200 V, 400 V, 600 V, 800 V, 1000 V, 1600 V					
I _{FSM}	30 A					
I _R	1.0 μΑ					
V_{F}	1.15 V					
E _R	20 mJ					
T _J max.	150 °C					
Package	DO-214AC (SMA)					
Diode variations	Single die					

FEATURES

- Low profile package
- Ideal for automated placement
- Controlled avalanche characteristics
- Glass passivated junction
- · Low reverse current
- · High surge current capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Material categorization: For definitions of compliance please see <u>www.vishav.com/doc?99912</u>

TYPICAL APPLICATIONS

For use in general purpose rectification of power supplies, inverters, converters, and freewheeling diodes for consumer, automotive, and telecommunication.

MECHANICAL DATA

Case: DO-214AC (SMA)

Molding compound meets UL 94 V-0 flammability rating Base P/N-E3 - RoHS-compliant, commercial grade Base P/NHE3 - RoHS-compliant, AEC-Q101 qualified

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

E3 suffix meets JESD 201 class 2 whisker test, HE3 suffix meets JESD 201 class 2 whisker test

Note

• BYG10Y for commercial grade only

Polarity: Color band denotes the cathode end

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)								
PARAMETER	SYMBOL	BYG10D	BYG10G	BYG10J	BYG10K	BYG10M	BYG10Y	UNIT
Device marking code		BYG10D	BYG10G	BYG10J	BYG10K	BYG10M	BYG10Y	
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	1600	V
Average forward current	I _{F(AV)}	I _{F(AV)} 1.5					Α	
Peak forward surge current 10 ms single half sine-wave superimposed on rated load I _{FSM} 30							Α	
Pulse energy in avalanche mode, non repetitive (inductive load switch off) $I_{(BR)R} = 1 \text{ A}, T_J = 25 ^{\circ}\text{C}$ (for BYG10D thru BYG10M) $I_{(BR)R} = 0.4 \text{A}, T_J = 25 ^{\circ}\text{C}$ (for BYG10Y)	E _R	20					mJ	
Operating junction and storage temperature range	T _J , T _{STG}	- 55 to + 150					°C	



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ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)										
PARAMETER	TEST CONDITIONS		SYMBOL	BYG10D	BYG10G	BYG10J	BYG10K	BYG10M	BYG10Y	UNIT
Maximum	I _F = 1 A				1.1					
instantaneous forward voltage ⁽¹⁾	I _F = 1.5 A	T _J = 25 °C	V _F	1.15					V	
Maximum DC	$V_R = V_{RRM}$	T _J = 25 °C	T _J = 25 °C		1					μA
reverse current	VR - VRRM	T _J = 100 °C			10					μΑ
Maximum reverse recovery time	$I_F = 0.5 A, I_R$ $I_{rr} = 0.25 A$	= 1.0 A,	t _{rr}	4				μs		

Note

 $^{^{(1)}\,}$ Pulse test: 300 μs pulse width, 1 % duty cycle

THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)								
PARAMETER	SYMBOL	MBOL BYG10D BYG10G BYG10J BYG10K BYG10M BYG10				BYG10Y	UNIT	
Typical thermal resistance, junction to lead	$R_{\theta JL}$	25						°C/W
	$R_{\theta JA}^{(1)}$	150						
Typical thermal resistance, junction to ambient	R ₀ JA (2)	125						°C/W
	R ₀ JA (3)	100						

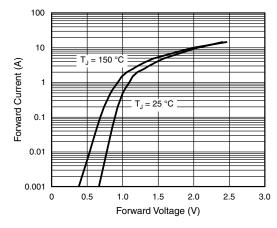
Notes

- (1) Mounted on epoxy-glass hard tissue
- (2) Mounted on epoxy-glass hard tissue, 50 mm² 35 μm Cu
- (3) Mounted on Al-oxide-ceramic (Al₂O₃), 50 mm² 35 µm Cu

ORDERING INFORMATION (Example)								
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE				
BYG10D-E3/TR	0.064	TR	1800	7" diameter plastic tape and reel				
BYG10D-E3/TR3	0.064	TR3	7500	13" diameter plastic tape and reel				
BYG10DHE3/TR (1)	0.064	TR	1800	7" diameter plastic tape and reel				
BYG10DHE3/TR3 (1)	0.064	TR3	7500	13" diameter plastic tape and reel				

Note

RATINGS AND CHARACTERISTICS CURVES (T_A = 25 °C unless otherwise noted)





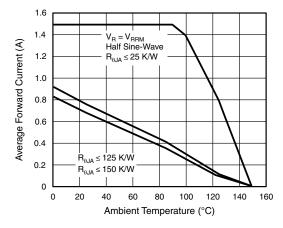


Fig. 2 - Max. Average Forward Current vs. Ambient Temperature

⁽¹⁾ AEC-Q101 qualified



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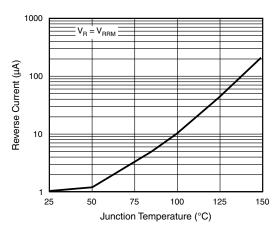


Fig. 3 - Reverse Current vs. Junction Temperature

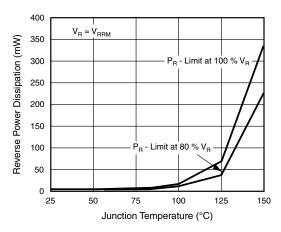


Fig. 4 - Max. Reverse Power Dissipation vs. Junction Temperature

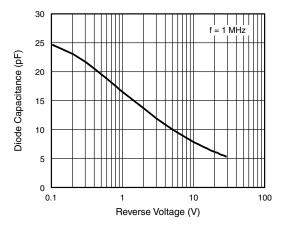


Fig. 5 - Diode Capacitance vs. Reverse Voltage

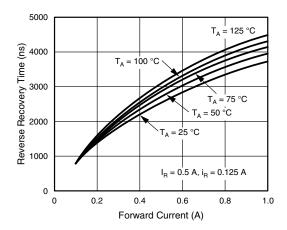


Fig. 6 - Reverse Recovery Time vs. Forward Current

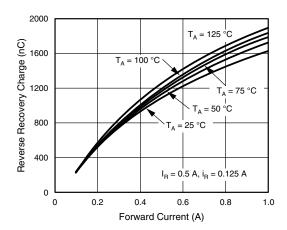


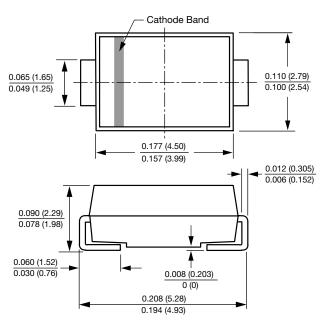
Fig. 7 - Reverse Recovery Charge vs. Forward Current



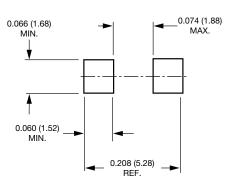
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PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

DO-214AC (SMA)



Mounting Pad Layout





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